

Or 11765

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Olgado, et al.

Serial No.: 10/043,561

Confirmation No.: 7947

Filed: January 8, 2002

For: SYSTEM FOR PLANARIZING
METAL CONDUCTIVE LAYERS



Group Art Unit: 1765

Examiner: Kin Chan Chen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on 5/21/03, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

5/21/03

Kin Chan Chen

Date Signature

RESPONSE TO RESTRICTION REQUIREMENT DATED APRIL 24, 2003

In response to the Restriction Requirement dated April 24, 2003, having a shortened statutory period for response set to expire on May 24, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/6060/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

THE PENDING CLAIMS:

1. A method of planarizing a metal conductive layer on a top surface of a substrate, comprising:
 - (a) placing the substrate on a rotatable substrate support;
 - (b) rotating the substrate support; and
 - (c) contacting the top surface of the substrate with a liquid etching